

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of:

Attorney Docket No.: ROH-030

Keiichi DEN

Application No.: 09/702,870

Examiner: L. C. Thai

Filed: November 1, 2000

Art Unit: 2811

For: SEMICONDUCTOR DEVICE OF CHIP-ON-CHIP STRUCTURE WITH  
RADIATION NOISE SHIELD (as amended)

**REQUEST FOR APPROVAL OF DRAWING CORRECTIONS**

COMMISSIONER FOR PATENTS  
Washington, DC 20231

Sir:

In accordance with U.S. Patent and Trademark Office practice, proposed drawing changes, shown in red ink on the attached informal drawings, are attached, wherein Applicants propose to amend the drawings in the above-identified application as follows:

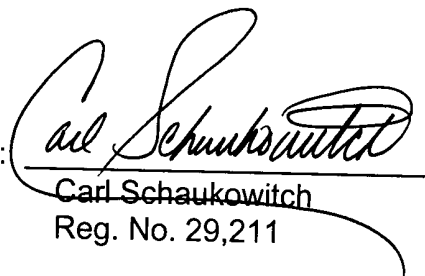
Please amend Figures 3, 4 and 5 as shown in red.

No new matter has been added. Approval is earnestly requested.

Respectfully submitted,

Date: March 19, 2002

By:

  
Carl Schaukowitch  
Reg. No. 29,211

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Enclosures: Three (3) sheets of drawings (Figs. 3, 4 and 5)



#6  
Drawing  
J. V. Ho  
4-1-02

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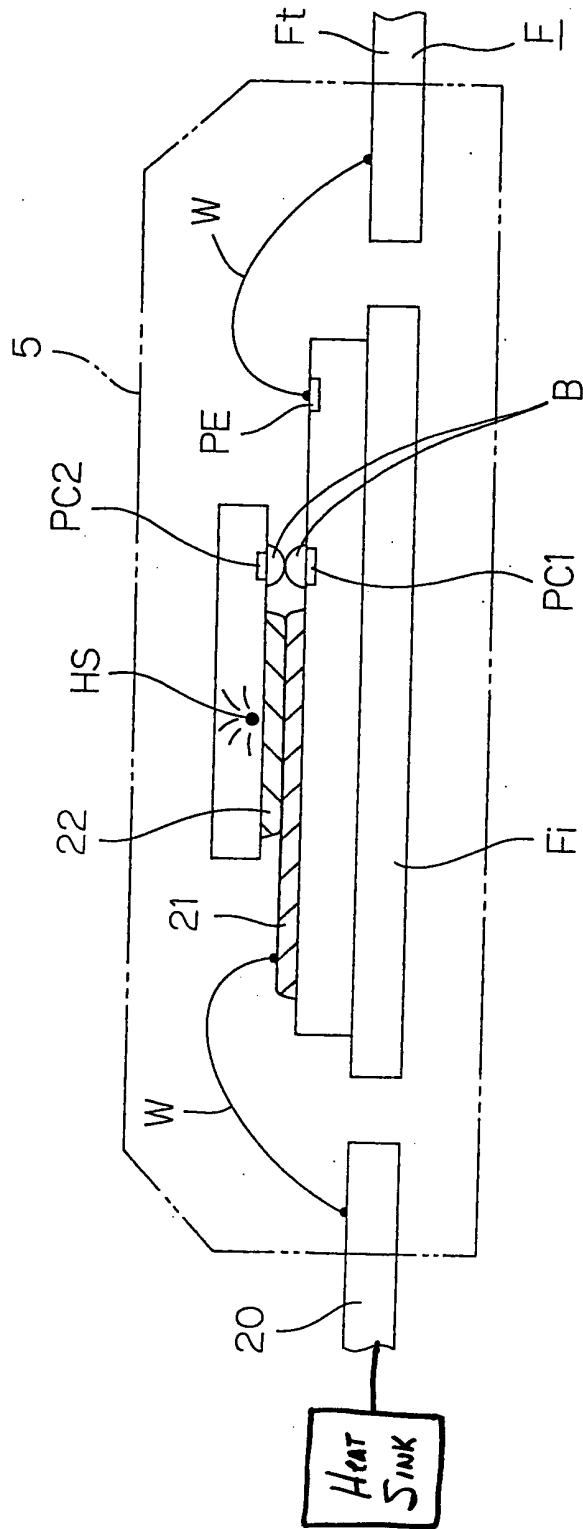
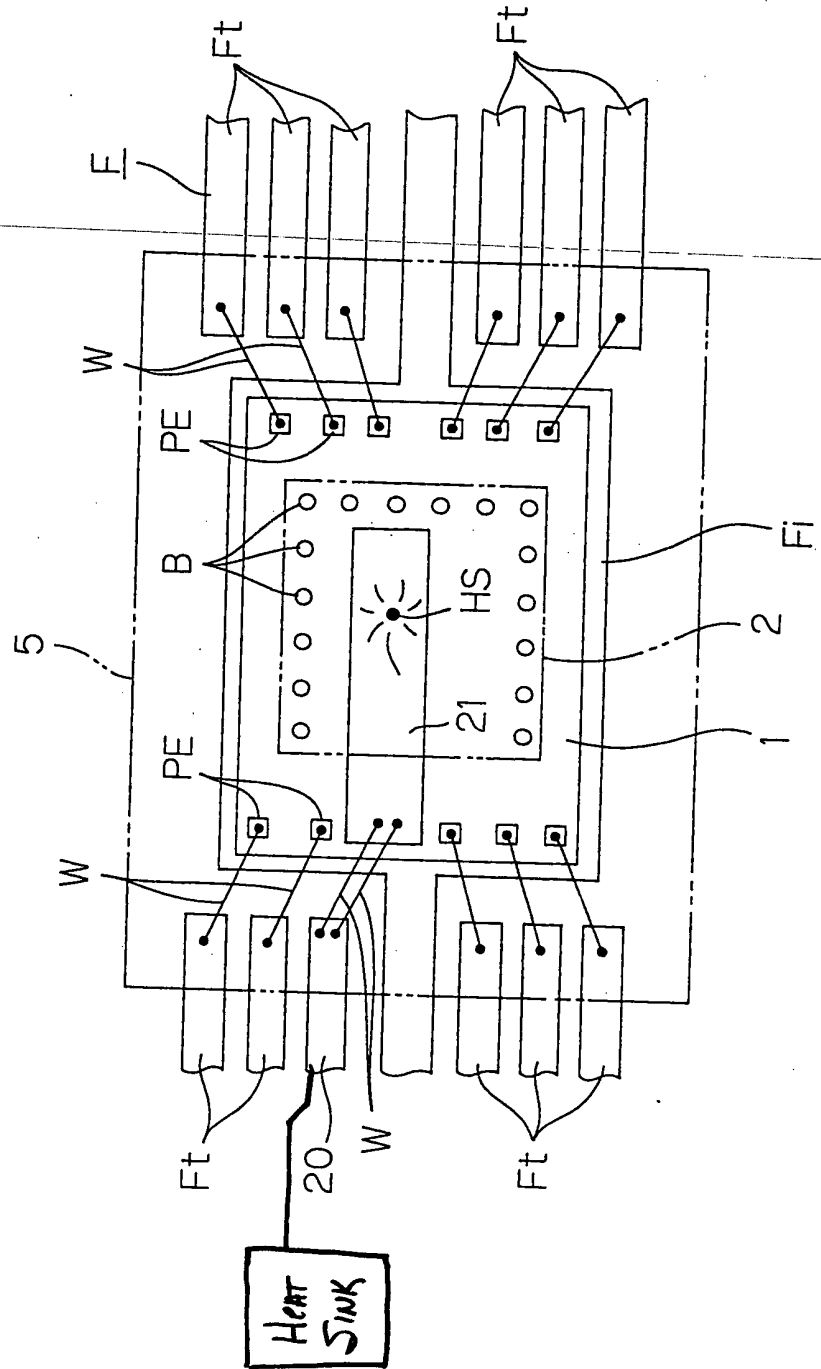
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FIG. 4



A cross-sectional diagram of a semiconductor device assembly. At the bottom left, a box labeled "Heat Sink" is connected by a vertical line to a rectangular component labeled "20". Above component "20" are two stacked layers: "Ftp" (bottom) and "PC1" (top). To the right of component "20" is another layer labeled "Fi". A central vertical stack consists of layers "NS" and "HS" separated by a dashed horizontal line. Below "NS" is a hatched layer labeled "21". Above "HS" is a hatched layer labeled "22". On top of "22" is a small rectangular component labeled "PE". To the right of "PE" is a larger rectangular component labeled "B". Above "B" is a layer labeled "PC2". The entire assembly is enclosed in a dashed-line boundary labeled "5". Several curved arrows, each labeled "W", indicate heat flow paths from components "20", "PE", and "B" towards the central "NS"/"HS" interface. At the top center, there is a circular feature with four arrows pointing outwards, labeled "HS". To the right of this feature is a label "Ft". At the far right edge, there is a label "E".

